

# CBTVS2A12-1F3

**Datasheet - production data** 

## Circuit breaker with transient voltage suppressor



### Figure 1. Pin configuration (bump side)



Figure 2. Configuration<sup>(a)</sup>



a. B1 and B2 bumps must be grounded on the PCB together.

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## Features

- Transient voltage suppressor (TVS)
- Non-resettable over current protection (OCP)
- Electrostatic discharge protection
- Electrical overstress protection (OVP)
- Unidirectional device
- Fast response time
- Very thin package: 0.4 mm
- High ESD protection level
- High integration
- Suitable for high density boards

### Complies with the following standards:

- IEC 61000-4-2 level 4:
  - ±15 kV (air discharge)
  - ±15 kV (contact discharge)

## Description

The CBTVS2A12-1F3 is a single line diode TVS integrating a fuse designed specifically for the protection of integrated circuits in portable equipment and miniaturized electronics devices subject to ESD, OVP and OCP.

This is information on a product in full production.

# 1 Characteristics

Symbol	Parameter	Test condition	Value	Unit	
V	Peak pulse voltage	IEC 61000-4-2 contact discharge	15	– kV	
V <sub>PP</sub>		IEC 61000-4-2 air discharge	15		
P <sub>PP</sub>	Peak pulse power dissipation	10/1000 $\mu$ s pulse, on A2-B2, T <sub>j</sub> = T <sub>amb</sub>	44	— w	
		8/20 µs pulse, on A2-B2, T <sub>j</sub> = T <sub>amb</sub>	350		
Тj	Maximum operating junction temperature		125	°C	
T <sub>stg</sub>	Storage temperature range		-55 to +150	°C	

Table 1. Absolute maximum ra	atings ( $T_{\rm max} = 25$ °C)
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Figure	3	Electrical	characteristics	(definitions)
Iguie	э.	Liectifical	characteristics	(ueminions)

Symb	ol	Parameter	IF
$V_{BR}$	=	Breakdown voltage	• <b>F</b>
V <sub>CL</sub>	=	Clamping voltage	
I <sub>RM</sub>	=	Leakage current @ V <sub>BM</sub>	
V <sub>RM</sub>	=	Stand-off voltage	
l <sub>F</sub>	=	Forward current	
R <sub>d</sub>	=	Dynamic impedance	l l l l l l l l l l l l l l l l l l l
I <sub>PP</sub>	=	Peak pulse current	
I <sub>R</sub>	=	Breakdown current	
V <sub>F</sub>	=	Forward voltage drop	Slope = 1/Rd

## Table 2. Electrical characteristics (at operating temperature: $T_{op}$ = -30 °C to +85 °C, unless otherwise specified)

Symbol	Test conditions	Min.	Тур.	Max.	Unit
V <sub>BR</sub>	$I_R = 1 \text{ mA}, T_{amb} = 25 \text{ °C}$	12			V
I <sub>RM</sub>	$V_{RM}$ = 10 V, at $T_{amb}$ = 25 °C			100	nA
V <sub>CL</sub>	$I_{PP}$ = 1 A, 8/20 µs pulse waveform, between A1-B1 at $T_{amb}$ = 25 °C			15	V
V <sub>F</sub>	I <sub>F</sub> = 850 mA, between A1-B1			1.4	V
C <sub>line</sub>	$V_R = 0 V$ , $V_{OSC} = 30 mV$ , $F = 1 MHz$		180		pF
R <sub>A1-A2</sub>	At T <sub>amb</sub> = 25 °C at 100 mA			50	mΩ
R <sub>A1-A2</sub>	After fused	1			MΩ
T <sub>Fuse</sub>	At 5 A (maximum opening time) A <sub>1</sub> -A <sub>2</sub> , A <sub>2</sub> -A <sub>1</sub>			100	ms
T <sub>Fuse2</sub>	At 3.2 A, A <sub>1</sub> -A <sub>2</sub> , A <sub>2</sub> -A <sub>1</sub>			24	hours
T <sub>fuse Lifetime</sub>	$I_{DC} = 2 \text{ A}$ (continuous current) at $T_{amb} = 25 \text{ °C}$	500			hours



Tj init = 25 °C

1.1 1.2 1.3 1.4 1.5 1.6 1.7 1.8 1.9 2 V<sub>EM</sub>(V

#### Figure 4. Clamping voltage versus peak pulse current (typical values)







Figure 8. ESD response to IEC 61000-4-2 (+8 kV contact discharge)



Figure 5. Forward voltage drop versus peak

forward current (typical values)

I<sub>FM</sub> (A)

0.6 0.7 0.8 0.9

1

10

0.1

0.01



Figure 9. ESD response to IEC 61000-4-2 (-8 kV contact discharge)



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# 2 Ordering information scheme

Figure	10.	Ordering	information	scheme
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## 3 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <u>www.st.com</u>. ECOPACK<sup>®</sup> is an ST trademark.









#### Figure 14. Tape and reel specifications





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Note:More information is available in the application notes:AN2348: "400 μm Flip Chip: Package description and recommendations for use"AN1751: "EMI Filters: Recommendations and measurements"

# 4 Ordering information

Table 5. Ordering mormation					
Order code	Marking	Package	Weight	Base qty	Delivery mode
CBTVS2A12-1F3	EB	Flip Chip	0.659 mg	10 000	Tape and reel (7")

### Table 3. Ordering information

# 5 Revision history

Table 4. Document	revision history
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Date	Revision	Changes
19-May-2014	1	Initial release.



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